98. The method as recited in claim 15, wherein the reflowable material is the only material that contacts the metallization and the pad after the reflowing.

99. The method as recited in claim 15, wherein the reflowable material is the only conductor external to the chip that contacts the pad after the reflowing.

100. The method as recited in claim 25, wherein the solder joint extends continuously between the first and second surfaces in the via hole.

101. The method as recited in claim 25, wherein the solder joint is the only material in the via hole that contacts the metallization.

102. The method as recited in claim 25, wherein the solder joint is the only material in the via hole that contacts the pad.

103. The method as recited in claim 25, wherein the solder joint is the only material that contacts the metallization and the pad.

104. The method as recited in claim 25, wherein the solder joint is the only conductor external to the chip that contacts the pad.

105. The method as recited in claim 50, wherein the solder joint extends continuously between the first and second surfaces in the via hole.

106. The method as recited in claim 50, wherein the solder joint is the only material in the via hole that contacts the metallization.

107. The method as recited in claim 50, wherein the solder joint is the only material in the via hole that contacts the pad.

108. The method as recited in claim 50, wherein the solder joint is the only material that contacts the metallization and the pad.

109. The method as recited in claim 50, wherein the solder joint is the only conductor external to the chip that contacts the pad.

110. The method as recited in claim 55, wherein the solder joint extends continuously between the first and second surfaces in the via hole.

111. The method as recited in claim 55, wherein the solder joint is the only material in the via hole that contacts the metallization.

112. The method as recited in claim 55, wherein the solder joint is the only material in the via hole that contacts the pad.

113. The method as recited in claim 55, wherein the solder joint is the only material that contacts the metallization and the pad.

114. The method as recited in claim 55, wherein the solder joint is the only conductor external to the chip that contacts the pad.

115. The method as recited in claim 60, wherein the solder joint extends continuously between the first and second surfaces in the via hole.

116. The method as recited in claim 60, wherein the solder joint is the only material in the via hole that contacts the metallization.

117. The method as recited in claim 60, wherein the solder joint is the only material in the via hole that contacts the pad.

118. The method as recited in claim 60, wherein the solder joint is the only material that contacts the metallization and the pad.

119. The method as recited in claim 60, wherein the solder joint is the only conductor external to the chip that contacts the pad.